# Construction of the Scintillating Fibre Tracker Challenges and lessons learned

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### **SciFi Overview**



Modular design (mechanics, modules, electronics) - very successful

# **The Project Organisation (Production)**



LHCh



# Scintillating Fibre – industrial supplier

#### **Challenges:**

11000 km Radiation hardness of fibres Light-yield & attenuation length Homogenity Cladding Production & price



#### Scan every milimeter: measure diameter, check cladding.



Fast acceptance check of all fibres by one lab (CERN) was important!



## **Biggest Problem: Bumps**



Significant number of "bumps" >350 µm: destroy winding pattern of mats.

 $\rightarrow$  even w/ optimization of production process producer was unable to eliminate the "big" bumps (had to accept in average 8 bumps per 12 km)

Even experienced producers cannot always provide flawless products.



### **Bump Removal**



Automatic bump shrinkage using a "hot drawing" tool. Applied routinely.



Caveat:

1-2 bumps per spool are larger than 500 mm  $\rightarrow$  shrinking fails.

Those were manually removed by cutting & gluing.

UV curing glue: t = 10-15s per bump.



# **Production quality was excellent**



Spool lot number





LHCh



Stored reference samples show a slight decrease of the attenuation length over time due to oxidation.



Observed already before by producer and others. Surprising for us. Not critical for the operation of SciFi.

The more you check the more problems you find!



### **Fibre Mat Production**

About 1100 + spares mats (130 mm  $\times$  2.5 m) needed  $\rightarrow$  4 production centres

Four equal winding machines prodcued in industry:





## **Optimization of Mat Production**



Be open for optimization steps even if they deviate from TDR design.



# **Production Organigramm**



### **Quality Assurance: Winding Pattern**





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#### **Light Yield & Mirror Reflectivity**

For every mat: light yield before and after mirrow glueing







## **Production Schedule**





### **Module Production**





#### Initial problems:

- Lateral bending of mats
- Shrinkage of fibre mats
- alu endplugs incorrect
- → immediate feedback to winding centres

LHCP THCP SC F

### "Academic" TDR Design: beam-pipe cut-out



From round - ideal but unfeasible - to rectangular and identical for all layers

Review the TDR design with a critical eye!

### Every step was monitored for every module

#### Cutting of fibre mats to the correct widths $\rightarrow$ damage fibres



 $\Delta X / \mu m$ 

# **Cosmic test of all modules**

Another light yield test – complete module





### **Module Production Schedule**

#### Module production parallel to mat winding!





### **Production Database**

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Same database was used for production and assembly of all components: modules, electronics, coldboxes and final C-frames. This paid off!



#### **Coldboxes**





## **Module Finishing & QA w/ Cosmics**







## **Electronics Readout**



SciFi (528k channels) – 4096 GBT links (max. 2.3 TB/s) Correct modularity important: yield versus number of connections!



# **PACIFIC Frontend Chip (40 MHz)**



#### Minimal ASIC functionality:

- No ADC 3 thresholds to access the pulse height
- No digital data-processing → use FPGA
- 338 registers (8 bits) for chip configuration

#### History:

May 2013: PACIFICr0 (preamp) Nov 2013: PACIFICr1 (analog FE) Aug 2014: PACIFCr2 (8 chan analog)

Jul 2015: PACIFICr3 (full 8 chan, 130nm) Sep 2016: PACIFICr4 (opimization) Mar 2017: PACIFCr5 (production, different)

Test beams

If possible keep the ASIC simple. Chip designer should be involved in testing, the development of the carrier boards and in test beam studies!



## **ASIC Production and Carrier Board**

#### Packaging of preseries:



Company made mistake with unique QR codes in first batch: all chips are "Ser.No. 1", human readable number missing → laser etched chip numbers in Heidelberg instead





Anything than can go wrong will go wrong.

- All chips have been tested and qualified (tuning parameters measured).
- Carrier boards have been developed and produced in parallel
- Carrier boards have undergone again a similar test as the chips.

# **Cluster Boards using antifuse FPGA**

Clustering for noise supression and data compression ( $\rightarrow \times 0.5$ ):



Use antifuse FPGA (Microsemi IGLOO2) (expected radiation dose ~100 Gy 10krad)

Remark: CERN studies showed that these FPGAs still work at that level. Studies reported "problems w/ progammability"

 $\rightarrow$  our owvn test at CERN's irradiation facility: programmability can be lost after 1krad (~1 year)







#### 5100 FPGAs needed $\rightarrow$ international tendering required

Tendering procedure via CERN (VAT):

- ~4 month of preparation with the CERN purchaser officer to agree on the "best" procedure and produce all the documents.
- 1 month for the publication
- 1.5 month between the opening of the offers and the sending of the order (price negotiation, etc.) and not smooth at all!

Oder submitted: 25/07/2019 1st batch delivery: 25/10/2019 2nd batch delivery: 21/11/2019

Purchase process of expensive parts can easily take ~1 year.





Provide connections: LV Power HV (SiPM) Optical transceivers: Slow/Fast crtl, data links DC-DC power converter House-keeping FPGA

Many connectors!

#### Mechanically and electrically very demanding board!



## **Electronics Cooling**

Power dissipation of full Readout Box: 120 W  $\rightarrow$  30 KW SciFi Water cooling necessary – integrated in the mounting structure. Cooling structure connected to water cooled cooling-plates.



#### Cooling must be integral part of the front-end design!





## **Testing of finished Readout-Boxes**



before!!). Testing of the ROBs became a bottle neck for the C-frame assembly at the end of 2021.



All Readout Boxes have undergone a very detailed test (incl. bit error tests of all links).

Very time consuming: Required lengthy cleaning of the optical transceivers and the optical connectors (delicate operation).

Test developed as result of commissioning.





#### "Slice test" - test beam w/ full readout chain

#### before launching serial production



(Nearly) final readout electronics: PACIFIC-5q boards Master Boards (v3) 4 ×Cluster Boards (v2) + 12 (v3) w/ 2 different clustering algorithms MiniDAQ2 (PCI40 1<sup>st</sup> version) 32 optical links, 4096 channels



σ < 70 μm ε > 99%



# **Support Mechanics: C-Frames**



#### **Extruded aluminum I-profiles:**



Company (world leader) was a real pain! Extrusion quality sometimes very bad! Company unable to machine the profiles. Delivery schedules completely unreliable.

Don't rely on a single industrial producer!



### **Detailed 3D CAD-model of the C-frame**



Integration of all services was very difficult! Prototype was vey helpful.



### Full C-Frame Prototype (frame #0)



Fullsize prototype including services, electronics and modules etc. Extremely useful to test mechanics, cabling paths, electronics readout ... Expensive but extremely valuable investment!



### 1<sup>st</sup> final C-frame (Jun 2019) – full operation



Condensation on vacuum insulated cooling pipes, cold-box, dry air exhaust. Full commissioning and operation of the 1<sup>st</sup> C-frame revealed system problems which could not have not been before: noise on LV, condensation<sub>36</sub>



### **Mitigation of Condensation**



We launched a detailed study mitigate the problem using active heating  $\rightarrow$  after review in Oct 2019 we continued with the assembly. Be prepared for system effects which only show up with final detector.



#### Commissioning of all service systems and of Electronics:





### **C-frame Assembly & Commissioning at CERN**

	CF1	CF2	CF3	CF4	CF5	CF6	CF7
Location	Slot 2	Slot 1	Slot 4	TS-Cage	TS-Cage	Slot 3	Cavern
Mechanics	ok	ok	ok	ok	ok	In progress	ok
Water NOVEC Dry-gas	ok ok ok	ok ok ok	ok ok ok	ok ok	ok		ok
Modules	ok	ok	ok				
Cabling	ok	ok	ok	ok	ok		ok
Heating	ok	ok	ok				
Electronics	ok		ok				
Optical Fibres	ok		ok				
Commissioning	ok	In progress (NOVEC)	In progress (Electronics)				
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In February 2020 all components at CERN, work on 4 frames in parallel ...



## **Installation - Prototyping**





### **Test Installation of 2 empty frames**





### Installation of 1<sup>st</sup> 4 frames in May 2021



Installation and connection of C-frames went very smooth. Most time consuming was the connection of the optical links.



### **First SciFi Data**

mean TAE shift per SiPM (Run 241111)





Not working links: 0 / 1024 control links ~8 / 4096 data links

High functionality a result of the many tests that have been done



## Conclusion

#### My tips:

Dense QA for all components: testing, testing, testing (many issues we had initially overlooked to monitor popped up during the many tests we were doing).

Early and full-size prototypes of all components: The knowledge gain easily balances the additional costs and efforts.

#### **Electronics:**

Full chain tests already w/ an early version of the electronics. Realistic "slice test" of a larger system before serial production is launched.

Take Engineering Design and Production Readiness Review serious.

Purchase of material takes time. Don't trust quality of industrial suppliers..











# **Scintillating Fibre**

#### Kuraray SCSF-78





# **Fibre Quality Assurance**

#### Kuraray SCSF-78



Fibre scanner, LHCb-PUB-2015-009

- All fibre spools scanned for mechanical defects and irregularities (so far ~6000 km scanned).
- We observe "bumps" = local increase of diameter.
- Bumps >350 μm (typ. ~8 per 12500 m) produce irregularities in winding pattern and must be removed.
- Automatic bump shrinkage using a "hot drawing" tool. Applied routinely.

LHCb-PUB-2016-010





# **Silicon Photomultiplier**

#### Hamamatsu, H2016-HRQ





# **SiPM Cooling and Alignment - Coldbox**





Coldbox 3D printed Ti cooling bar, carry/align 16 SiPMs

SiPM on flex print



- Cold box (3D printed nylon) at each end of fibre module; houses 16 SiPMs at -40°C, aligned and in optical contact to fibre ends.
- **Challenges:** thermal insulation, humidity management inside box (total length 130m)
- Pre-series under production.



### **Clusterization**



#### PACIFICr4 ASIC



<u>A readout ASIC for the LHCb</u> <u>Scintillating Fibre (SciFi)</u> <u>tracker</u>, **X. HAN at TIPP 2017** 

<u>Clustering = key to noise / data reduction:</u> Dark count rate w/ 6×10<sup>11</sup> n<sub>eq</sub> / cm<sup>2</sup> ~14 MHz / channel

cluster rate 0.8 MHz / 128 channels calculate x-position of clusters